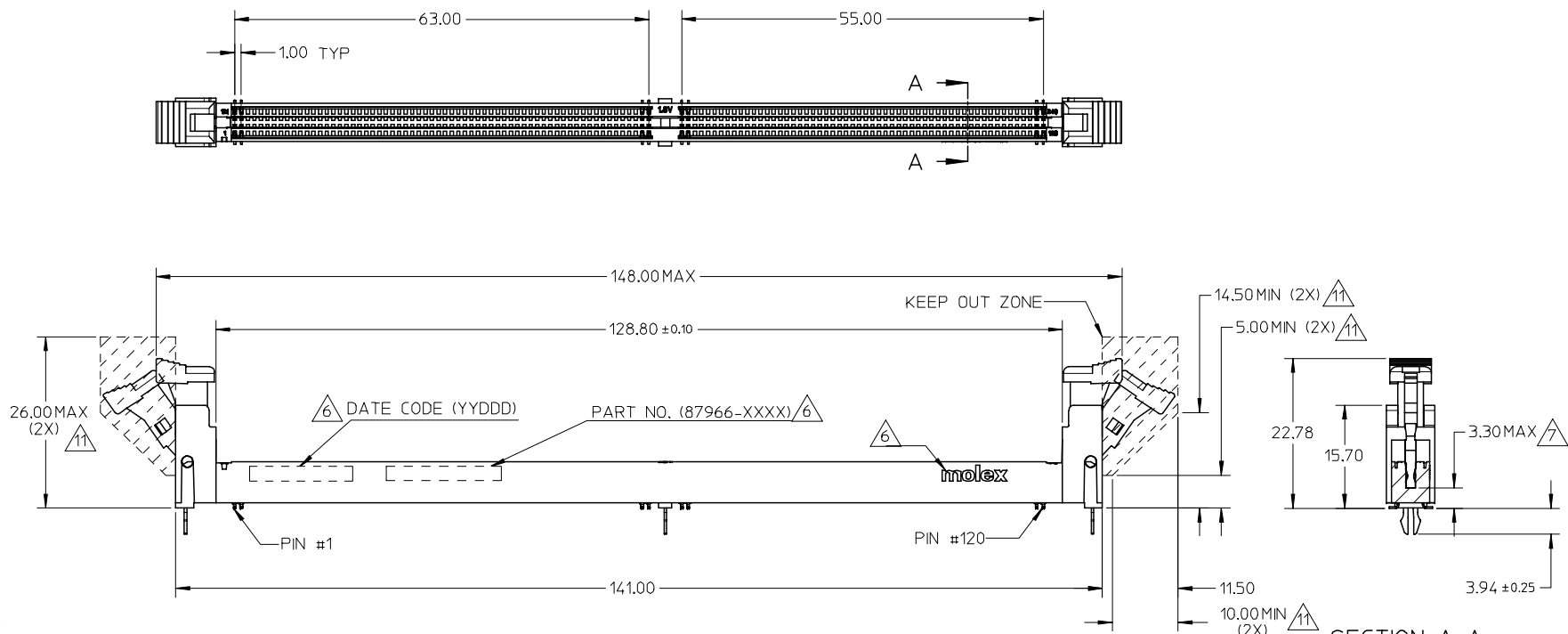




NOTES:

1. MATERIALS

HOUSING - HIGH TEMP LCP GLASS FILLED, UL 94V-0, BLACK
EJECTORS - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY

2. PLATING OPTION - PLS REFER TO SHEET 5.

3. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS, (MEASURED OVER PC PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237. PLS REFER TO SHEET 3.

5. PRODUCT IS PACKED INTO TRAYS.

6. MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.

7. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

8. COPLANARITY FOR SOLDER TAILS SHALL NOT EXCEED 0.20MM.

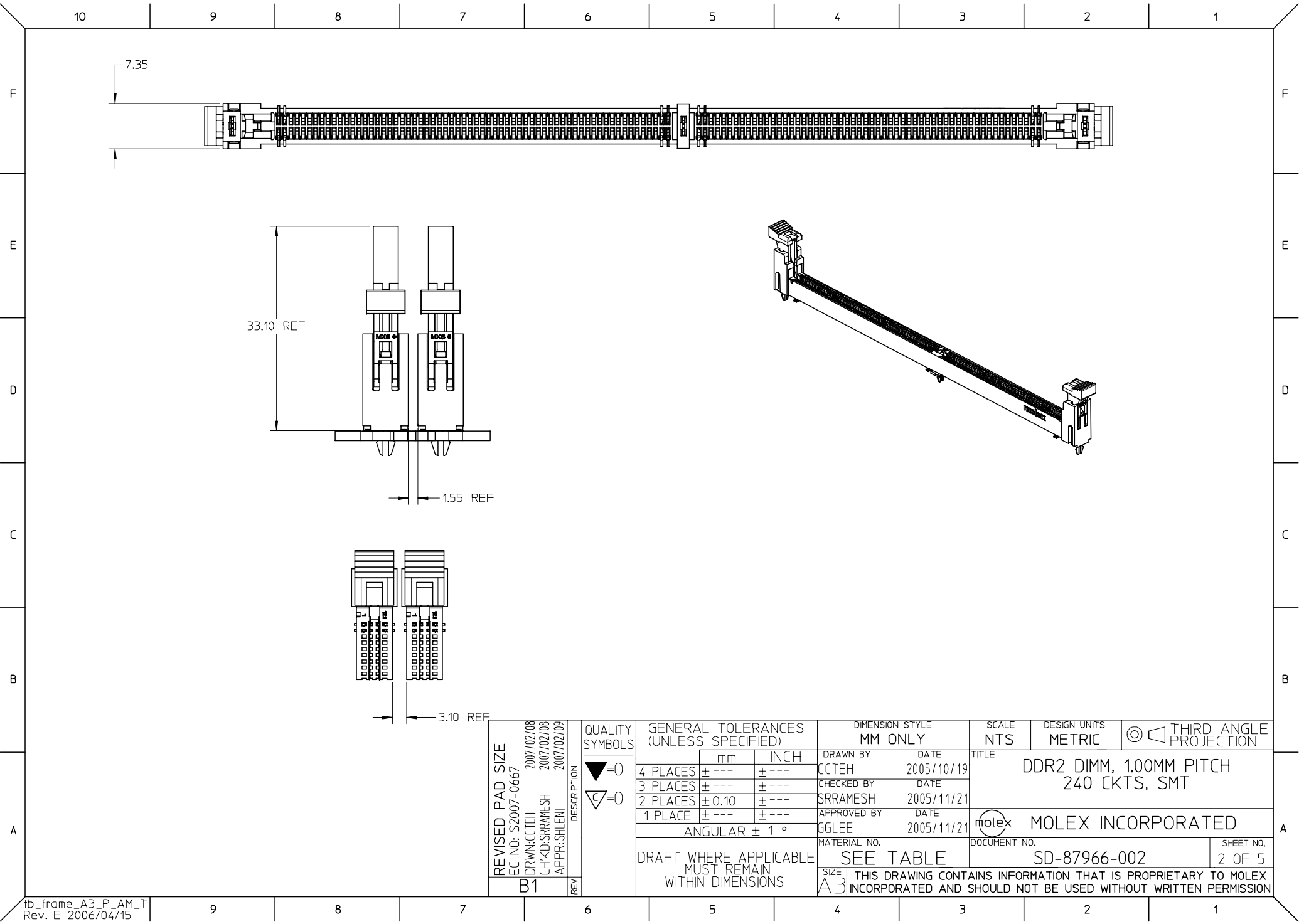
9. REFER TO PRODUCT SPEC. PS-87966-001 FOR PERFORMANCE SPECIFICATIONS.

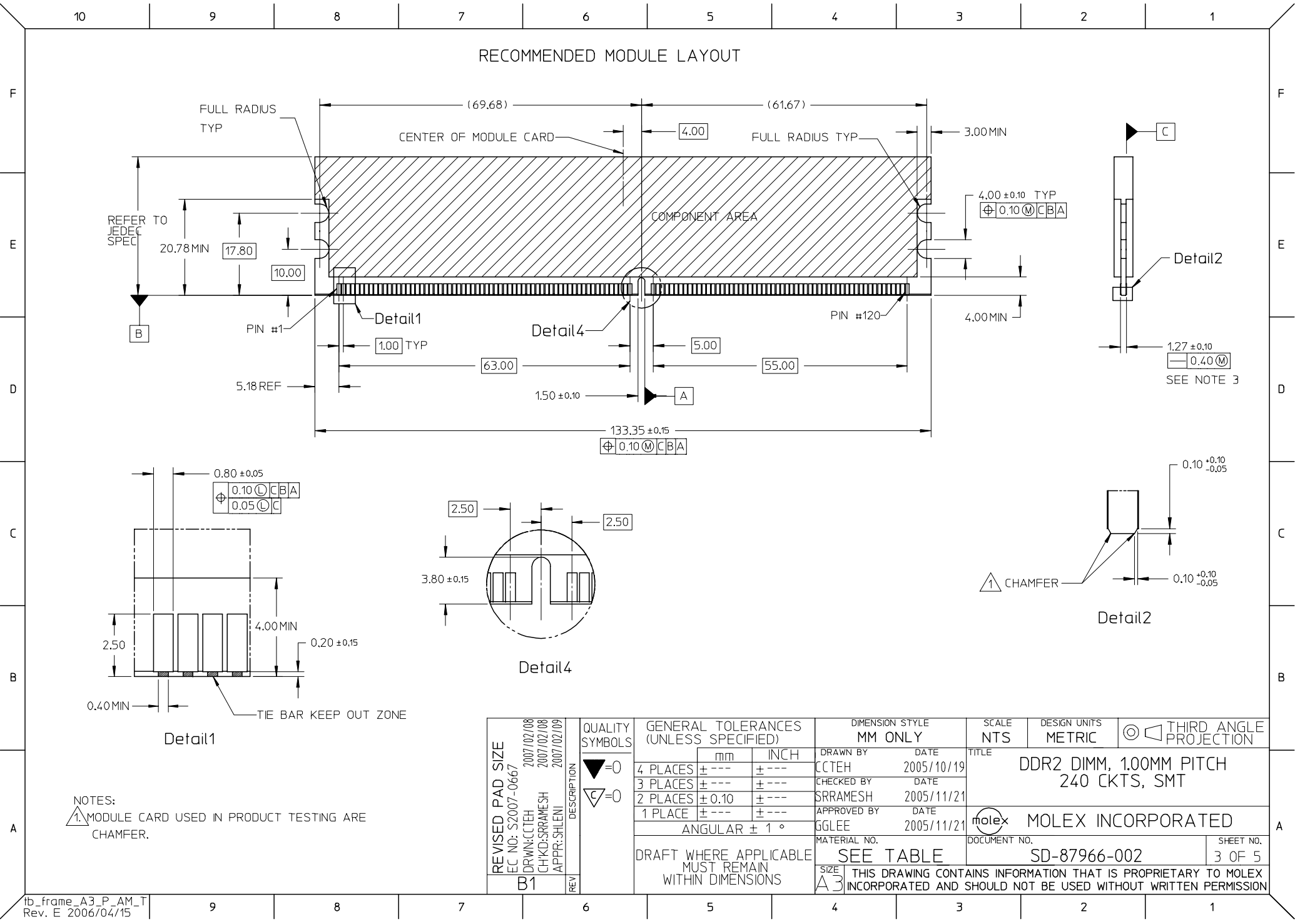
10. THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.

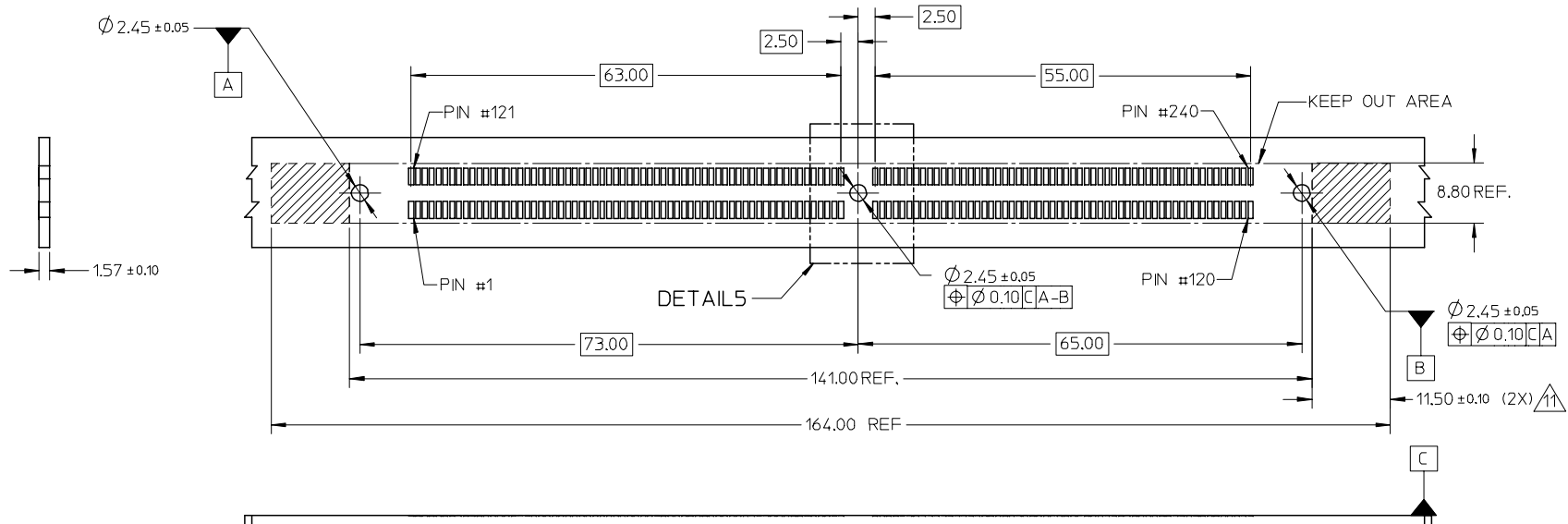
11. KEEP OUT ZONE AS PER JEDEC SO-001.

12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

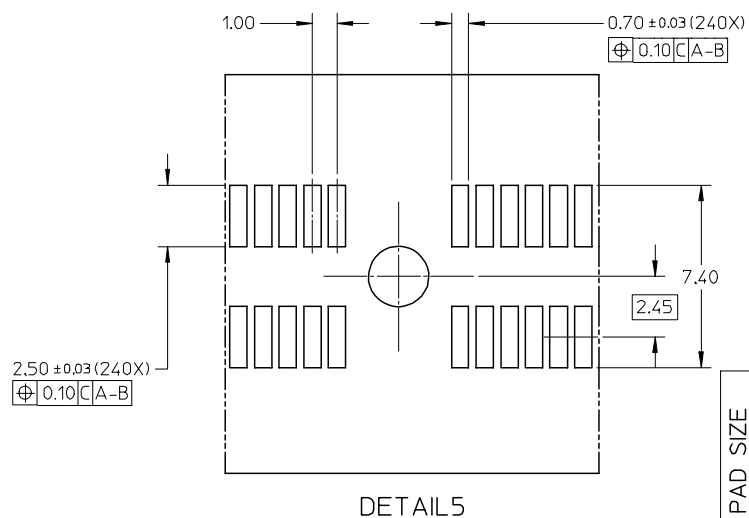
REVISED PAD SIZE			QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
EC NO: S2007-0667			▼=0		mm			DRAWN BY		NTS	METRIC	DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT	
2007/02/08			▽=0		INCH			DATE		TITLE			
DRWN: CTEH			4 PLACES ± --- ± ---			CCTEH			2005/10/19		MOLEX INCORPORATED		
2007/02/08			3 PLACES ± --- ± ---			CHECKED BY			DATE				
CHKD: SRRAMESH			2 PLACES ± 0.10 ± ---			SRRAMESH			2005/11/21		SD-87966-002		
2007/02/09			1 PLACE ± --- ± ---			APPROVED BY			DATE				
			ANGULAR ± 1 °			GGLLEE			2005/11/21		1 OF 5		
			DRAFT WHERE APPLICABLE			MATERIAL NO.			DOCUMENT NO.				
			MUST REMAIN			SEE TABLE							
			WITHIN DIMENSIONS			SIZE							
B1			REV			A3							
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													







RECOMMENDED STENCIL THICKNESS = 150µM.



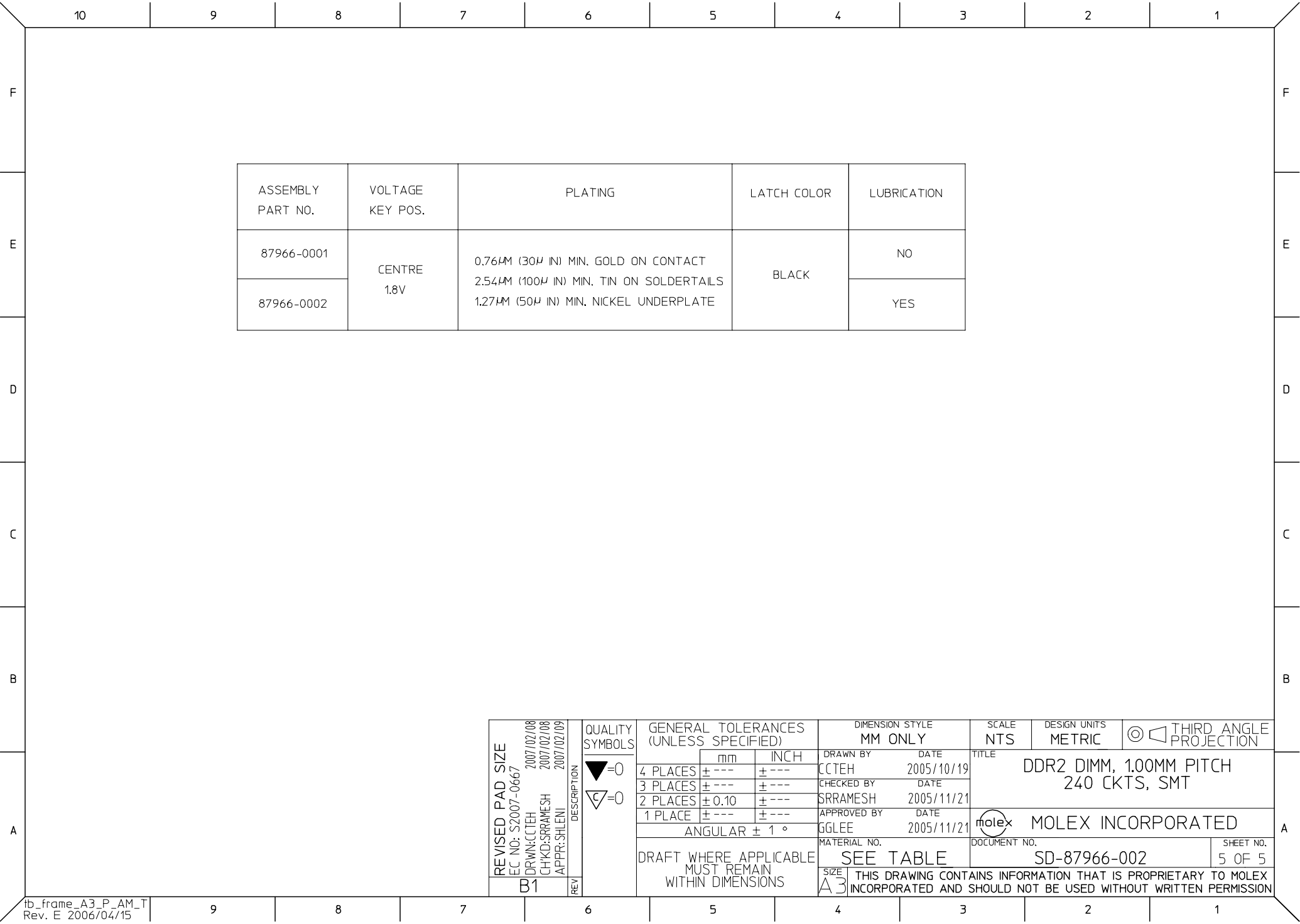
REV	DESCRIPTION
B1	REVISED PAD SIZE EC NO: S2007-0667 DRWN: CTEH 2007/02/08 CHKD: SRAMESH 2007/02/08 APPR: SILENI 2007/02/09

QUALITY SYMBOLS
▼ = 0
▽ = 0

GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CTEH	2005/10/19
CHECKED BY	DATE
SRAMESH	2005/11/21
APPROVED BY	DATE
GGLLEE	2005/11/21
MATERIAL NO.	
SEE TABLE	
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT		
MOLEX INCORPORATED		
DOCUMENT NO. SD-87966-002		SHEET NO. 4 OF 5



ASSEMBLY PART NO.	VOLTAGE KEY POS.	PLATING	LATCH COLOR	LUBRICATION
87966-0001	CENTRE 1.8V	0.76µM (30µ IN) MIN. GOLD ON CONTACT 2.54µM (100µ IN) MIN. TIN ON SOLDER TAILS 1.27µM (50µ IN) MIN. NICKEL UNDERPLATE	BLACK	NO
87966-0002				YES

REVISED PAD SIZE EC NO: S2007-0667 DRWN: CTEH CHKD: SRRAMESH APPR: SILENI B1	DESCRIPTION 2007/02/08 2007/02/08 2007/02/09	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87966-002		SHEET NO. 5 OF 5	